

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:

NEW ASSIGNMENT

NATURE OF CONVEYANCE:

ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
SCP IP, Inc.	10/02/2006

RECEIVING PARTY DATA

Name:	SCP Services, Inc.
Street Address:	6330 Hedgewood Drive, Suite 150
City:	Allentown
State/Country:	PENNSYLVANIA
Postal Code:	19103

PROPERTY NUMBERS Total: 6

Property Type	Number
Patent Number:	5972123
Patent Number:	6032682
Patent Number:	6132522
Patent Number:	6165912
Patent Number:	6245158
Patent Number:	6261845

CORRESPONDENCE DATA

Fax Number: (215)405-3805

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Correspondent Name: Wolf, Block, Schorr & Solis-Cohen

Address Line 1: 1650 Arch St.- 22nd Floor

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ATTORNEY DOCKET NUMBER:

AKR002-242786

PATENT

500260457

REEL: 019171 FRAME: 0463

OP \$240.00 5972123

NAME OF SUBMITTER:

Brian L. Belles

Total Attachments: 10

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INTELLECTUAL PROPERTY ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged, SCP Global Technologies, Inc., a Delaware corporation, and SCP IP, Inc., a Delaware corporation (together, "Assignors"), in connection with that certain Asset Purchase Agreement dated as of September 12, 2006 by and among Assignors, Aktron SCP Acquisition, Inc., a Delaware corporation ("Assignee"), Aktron, Inc., SCP U.S., Inc., SCP Services, Inc., and SCP International Netherlands, B.V., hereby sell, convey, assign, transfer and set over unto Assignee, its successors and assigns, all of its right, title and interest in and to all of the intellectual property held by Assignors, including but not limited to all patents, patent applications listed on Exhibit A and trademarks listed on Exhibit B attached hereto, including all continuations, continuations-in-part, divisionals, foreign counterparts and/or any patents, patent applications or trademarks claiming priority thereto, whether now existing or later filed, together with the goodwill of the business connected therewith, and registrations and applications therefor.

IN WITNESS WHEREOF, this Intellectual Property Assignment has been executed this 2nd day of October, 2006.

SCP GLOBAL TECHNOLOGIES, INC.

By: Keith G. O'Leary
Name: Keith G. O'Leary
Title: Chief Executive Officer

SCP IP, INC.

By: Keith G. O'Leary
Name: Keith G. O'Leary
Title: Executive Vice President

EXHIBIT A

App #	USPN	Title	Filed
	4,860,643	Ventilated Clean Room Work Station with Aerodynamic Exhaust Baffle	7/21/1988
	5,226,242	Vapor Jet Dryer Apparatus and Method	2/18/1992
	5,569,330	Method and device for chemically treating substrates	1/13/1995
	5,744,716	Fluid Displacement Level, Density and Concentration Measurement System	6/7/1995
	5,847,276	Fluid Displacement Level, Density and Concentration Measurement System	10/31/1997
	5,879,484	Method and device for wet processing substrates in a vessel	11/12/1997
	5,882,598	Wafer Gap Conductivity Cell for Characterizing Process Vessels and Semiconductor Fabrication Processes and Method of Use	6/7/1996
	5,902,402	Device for Chemical Wet Treatment	7/3/1997
	5,954,068	Device and Method for Treating Substrates in a Fluid Container	5/23/1997
	5,972,123	Methods for Treating Semiconductor Wafers	6/12/1998
	6,041,938	Compliant Process Cassette	8/27/1997
	6,132,522	Wet Processing Methods for the Manufacture of Electronic Components Using Sequential Chemical Processing	7/19/1996
	6,136,724	Multiple Stage Wet Processing Chamber	2/18/1998
	6,138,694	Multiple Stage Wet Processing Platform and Method of Use	3/5/1999
	6,145,520	Apparatus for Processing Substrates in a Fluid Tank	10/23/1998
	6,153,533	Method of Using a Compliant Process Cassette	1/21/1999
	6,165,912	Electroless Metal Deposition of Electronic Components in an Enclosable Vessel	9/14/1999
	6,170,703	Chemical Dispensing System and Method	1/8/1999
	6,189,552	Substrate Processing Device	5/24/1999
	6,240,938	Device for Treating Substrates in a Fluid Container	12/6/1996
	6,244,282	Substrate treatment device	5/1/1999
	6,245,250	Process Vessel	3/5/1999
	6,264,036	Process Cassette	3/5/1999
	6,257,255	Substrate treatment device	4/23/1999
	6,269,822	Installation for Wet-Treating Substrates	3/22/1999
	6,270,585	Device and process for treating substrates in a fluid container	3/19/1999
	6,286,688	Compliant Silicon Wafer Handling System	4/2/1997

	6,328,809	Vapor Drying System and Method	1/8/1999
	6,352,064	Substrate Treatment Device	4/23/1999
	6,360,921	Bellows-Type Dispensing Pump	6/2/2000
	6,379,096	Buffer Storage System	2/22/2000
	6,379,470	Method and Device for Treating Substrates	8/13/2001
	6,488,779	Method and Apparatus for Cleaning Substrates	12/13/2001
	6,488,987	Apparatus and Method for Processing Substrates	6/22/2001
	6,491,763	Processes for Treating Electronic Components	3/13/2001
	6,495,099	Wet Processing Methods for the Manufacture of Electronic Components	12/10/1998
	6,523,552	Facility for Treating Objects in a Process Tank	10/1/1996
	6,569,302	Substrate Carrier	6/22/2001
	6,607,604	Method and Apparatus for Treating Substrates	6/30/2000
	6,647,641	Device and Method for the Treatment of Substrates in a Fluid Container	12/3/1999
10/258,559	6,706,121	Device and method for the treatment of semiconductor wafers	10/23/2002
	6,730,177	Method and Apparatus for Washing and/or Drying Using a Revolved Coanda Profile	7/31/2002
	6,805,754	Device and method for treating substrates	9/28/2001
	6,378,544 B1	Pressure Relief Device and Method of Using the Same	4/19/2000
	6,246,158 B1	Wet Processing Methods for the Manufacture of Electronic Components Using Liquids of Varying Temperature	6/2/1999
	6,378,544 B1	Pressure Relief Device and Method of Using the Same	4/19/2000
09/145,192 US 2001-0047815		"Method for treating substrates" (Process sequence for Poseidon Single tank tool)	9/1/1998
09/209,101 09/930,009 US 2001-0104552	6,495,099	Wet Processing Methods for the Manufacture of Electronic Components	12/10/1998
		System and Methods for Forming Processing Streams	8/15/2001
10/031,923	6,799,588	Apparatus for Treating Substrates	4/17/2002
10/111,332	6,817,369	Device and method for treating substrates	4/18/2002
10/163,441 PrvI was 60/295,919 US 2003-0011774		Methods and Systems for Monitoring Process Fluids	6/4/2002
10/168,354 US 2002-0189651		Apparatus and Method for the Treatment of Substrates	6/14/2002
10/169,058 US 2003-0019744		Substrate holder	7/17/2002

10/169,060 US 2003-0029480		Apparatus for the Treatment of Substrates	8/22/2002
10/240,618 US 2003-0108409		Method for loading and unloading a processing tank	11/7/2002
60/168,487 09/727/661 US 2002-0066717-A1 on 6/6/2002		Apparatus for Providing Ozonated Process Fluid and Methods for Using Same	12/1/2000
60/270,815 10/074,516 US2002-0119245-A1		Method for Etching Electronic Components Containing Tantalum	2/13/2002
60/337,208 10/299,308 US 2003-0096457		Sonic Transducers Bonded with Polymers and Methods of Making Same for Efficient Sonic Energy Transfer	11/19/2002
US 2003-0093917		Apparatus & Methods for Processing Electronic Component Precursors	11/21/2002

App #	USPN	Title
	4,577,650	Vessel and system for treating wafers with fluids
	4,633,893	Apparatus for treating semiconductor wafers
	4,738,272	Vessel and system for treating wafers with fluids
	4,740,249	Method of treating wafers with fluid
	4,778,532	Process and apparatus for treating wafers with process fluids
	4,795,497	Method and system for fluid treatment of semiconductor wafers
	4,856,544	Vessel and system for treating wafers with fluids
	4,899,767	Method and system for fluid treatment of semiconductor wafers
	5,383,484	Static megasonic cleaning system for cleaning objects
	5,744,716	Fluid displacement level, density and concentration measurement system
	5,879,464	Method and device for wet-processing substrates in a vessel
	6,032,662	Method for sulfuric acid resist stripping
	6,245,158	Wet processing methods for the manufacture of electronic components using liquids of varying temperature
	6,261,845	Methods and systems for determining chemical concentrations and controlling the processing of semiconductor substrates

	6,378,544	Pressure relief device and method of using the same
	6,517,636	Method for reducing particle contamination during the wet processing of semiconductor substrates
	6,730,177	Method and apparatus for washing and/or drying using a revolved coanda profile
	6,843,859	Dump door
	6,878,213	Process and system for rinsing of semiconductor substrates
	6,878,213	Process and system for rinsing of semiconductor substrates
09/905025		Vapor drying system and method
10/197384		Composition and method for removing photoresist and/or resist residue using supercritical fluids
10/501256		Apparatus and method for treating disc-shaped substrate
10/537996		Method for drying substrates
10/620895		Compositions and method for removing photoresist and/or resist residue at pressures ranging from ambient to supercritical

App #	USPN	Title	Filed
09/209,102			12/1/1998
09/913,985		"Device and method for treating substrates" (Poseidon Double Tank Tool)	2/1/2000
09/936,674		"Device for treating substrates" (Vertical double process chamber)	Mar 00
10/110,179		"Device and method for treating substrates" (Process rescue function)	9/1/2000
10/477,449		"Device for wet cleaning of disclike substrates" Single wafer Marangoni	11/1/2003
60/135,267 09/574,790		Methods for Wet Processing Electronic Components Having Copper Containing Surfaces	5/19/2000
60/331,733 10/301,332		Apparatus and Methods for Drying Electronic Component Precursors	11/21/2001

EXHIBIT B

Mark	Juris- diction	Owner Name	Status	Class/s	Appl'n / Regist'n Number	Filing or Reg'n. Date
KRONOS	US	Steag Micro Tech GMBH (Assignee in security release: SCP IP, Inc.)	Registered	7, 11, 37	2,558,579	4/09/2002
ECO-PLATE	US	Steag Micro Tech GMBH (Assignee in security release: SCP IP, Inc.)	Registered	7, 37	2,630,279	10/8/2002
BARRACUDA	US	Steag Micro Tech GMBH (Assignee in security release: SCP IP, Inc.)	Registered	7, 37	2,648,048	11/12/2002
ECLIPSE 300	US	SCP Global Technologies, Inc.	Registered	7	2,627,709	10/01/2002
GREENDRY	US	SCP Global Technologies, Inc.	Registered	7	2,741,020	07/29/2003
E200	US	SCP Global Technologies, Inc.	Registered	7	2,537,355	02/05/2002
FLUIDCALC	US	SCP Global Technologies, Inc.	Registered	9	2,497,707	10/16/2001
ECO-PLATE	S. Korea	SCP Germany GmbH	Registered	9, 37	4500041190000	11/07/2001
BARRACUDA	S. Korea	SCP Germany GmbH	Registered	9, 37, 42	4500054830000	05/29/2002
DAMAS- CLEAN	S. Korea	SCP Germany GmbH	Registered	7, 9, 37	4500003580000	09/02/1999
POSEIDON STT	S. Korea	SCP Germany GmbH	Registered	35, 36, 37, 39, 40, 41, 42, 43, 44, 45	4100543820000	04/01/1999
STEAG	S.	Stegeu Hamatek	Registered	35, 36, 37,	4100480590000	10/12/1998

HAMATECH & DESIGN	Korea	GmbH SCP Germany GmbH		39, 40, 41, 42, 43, 44, 45		
STEAG HAMATECH & DESIGN	S. Korea	Stegau Hamatek GmbH SCP Germany GmbH	Registered	7, 8, 9, 10, 11, 17, 21	4004258090000	10/21/1998
STEAG HAMATECH & DESIGN	S. Korea	Stegau Hamatek GmbH SCP Germany GmbH	Registered	6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22, 24, 26	4004215030000	09/16/1998
STEAG & DESIGN	S. Korea	SCP Germany GmbH	Registered	35, 36, 37, 39, 40, 41, 42, 43, 44, 45	4100416890000	03/13/1998
STEAG MICROTECH & DESIGN	S. Korea	SCP Germany GmbH	Registered	6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22, 24, 26	4003875250000	12/23/1997
STEAG MICROTECH & DESIGN	S. Korea	SCP Germany GmbH	Registered	7, 8, 9, 10, 11, 17, 21	4003790880000	10/22/1997
STEAG MICROTECH & DESIGN	S. Korea	SCP Germany GmbH	Registered	35, 36, 37, 39, 40, 41, 42, 43, 44, 45	4100340440000	01/08/1997
CAPILLARY COAT	S. Korea	SCP Germany GmbH	Registered	6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22, 24, 26	4003623700000	05/19/1997
STEAG MICROTECH	S. Korea	SCP Germany GmbH	Registered	7, 8, 9, 10, 11, 17, 21	4003577270000	03/12/1997
STEAG MICROTECH	S. Korea	SCP Germany GmbH	Registered	6, 7, 8, 9, 11, 12, 16, 17, 18, 19, 20, 21, 22,	4003595750000	04/11/1997

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State of Delaware
Secretary of State
Division of Corporations
Delivered 01:24 PM 10/27/2006
FILED 01:18 PM 10/27/2006
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*Certificate of Amendment
to the
Certificate of Incorporation
of
AKRION SCP ACQUISITION CORP.*

Pursuant to Section 242 of the General Corporation Law of the State of Delaware

Akrion SCP Acquisition Corp. (the "Corporation"), a corporation organized and existing under the laws of the State of Delaware, hereby certifies as follows:

FIRST: The name of the corporation is Akrion SCP Acquisition Corp. The original Certificate of Incorporation of the Corporation was filed with the Secretary of State of the State of Delaware on November 9, 2005, under the name Akrion SCP Acquisition Corp. (the "Certificate").

SECOND: The Board of Directors of the Corporation adopted a resolution setting forth a proposed amendment to the Certificate, declaring said amendment to be advisable and submitting such resolution to the sole stockholder for approval. The resolution setting forth the proposed amendment is as follows:

RESOLVED, that the Certificate of Incorporation of the Corporation be amended by changing Article FIRST thereof so that, as amended, said Article shall read as follows:

"FIRST: The name of the corporation is SCP Services, Inc."

THIRD: The sole stockholder approved said amendment pursuant to Section 228 of the General Corporation Law of the State of Delaware.

FOURTH: Said amendment was duly adopted in accordance with the provisions of Section 228 and 242 of the General Corporation Law of the State of Delaware.

FIFTH: The capital of the Corporation shall not be reduced under or by reason of said amendment.

IN WITNESS WHEREOF, the Corporation has caused this Certificate of Amendment to the Certificate of Incorporation to be signed by its Chief Financial Officer, this 24 day of October, 2006.

AKRION SCP ACQUISITION CORP.

By: 

W. James Whittle, Chief Financial Officer

PHILADELPHIA\2918334\1 192374.000

Delaware

PAGE 1

The First State

I, HARRIET SMITH WINDSOR, SECRETARY OF STATE OF THE STATE OF DELAWARE, DO HEREBY CERTIFY THE ATTACHED IS A TRUE AND CORRECT COPY OF THE CERTIFICATE OF AMENDMENT OF "AKRION SCP ACQUISITION CORP.", CHANGING ITS NAME FROM "AKRION SCP ACQUISITION CORP." TO "SCP SERVICES, INC.", FILED IN THIS OFFICE ON THE TWENTY-SEVENTH DAY OF OCTOBER, A.D. 2006, AT 1:18 O'CLOCK P.M.

A FILED COPY OF THIS CERTIFICATE HAS BEEN FORWARDED TO THE NEW CASTLE COUNTY RECORDER OF DEEDS.



4058993 8100

060989232

Harriet Smith Windsor

Harriet Smith Windsor, Secretary of State

AUTHENTICATION: 5153694

DATE: 10-27-06

PATENT

RECORDED: 04/18/2007

REEL: 019171 FRAME: 0474